

SOT1979-1

FBGA187, fine-pitch ball grid array package, 187 terminals,
0.5 mm pitch, 9 mm x 9 mm x 1.87 mm body

29 October 2018

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	FBGA187
Package style descriptive code	FBGA (fine-pitch ball grid array)
Mounting method type	S (surface mount)
Issue date	28-05-2018
Manufacturer package code	98ASA01247D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	9	-	mm
package width	-	9	-	mm
package height	-	1.87	-	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	187	-	



2 Package outline

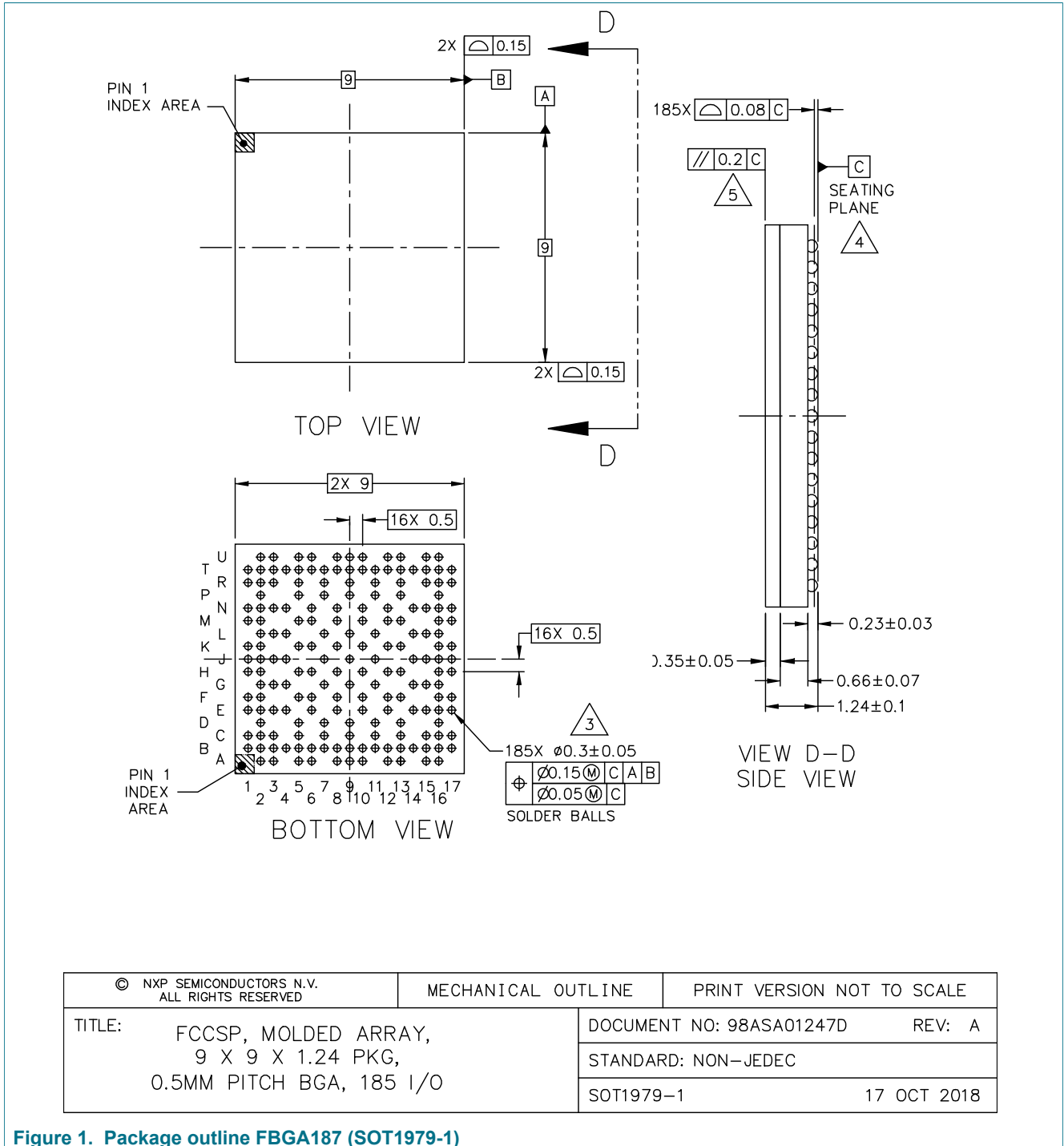


Figure 1. Package outline FBGA187 (SOT1979-1)

FBGA187, fine-pitch ball grid array package, 187 terminals, 0.5 mm pitch, 9 mm x 9 mm x 1.87 mm body

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C. RAW BALL DIAMETER IS 0.3MM.
4. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.
5. MAXIMUM SOLDER BUMP SHAPE MEASURED PARALLEL TO DATUM C.
6. ALL DIMENSIONS ARE SYMMETRIC ACROSS THE PACKAGE CENTER LINES, UNLESS DIMENSIONED OTHERWISE.

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TITLE: FCCSP, MOLDED ARRAY, 9 X 9 X 1.24 PKG, 0.5MM PITCH BGA, 185 I/O		DOCUMENT NO: 98ASA01247D	REV: A
		STANDARD: NON-JEDEC	
		SOT1979-1	17 OCT 2018

Figure 2. Package outline note FBGA187 (SOT1979-1)

3 Legal information

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